

IN THE SPECIFICATION

Please insert the following subtitle between lines 2 and 3 at page 1:

FIELD OF THE INVENTION

Please insert the following subtitle between lines 5 and 6 at page 1:

DISCUSSION OF THE BACKGROUND

Please replace the paragraph beginning at page 2, lines 6-12, with the following rewritten paragraph:

In addition, another related-art modular jack having a different structure from that of U.S. Patent Document 1 6,319,064 is also known. In this structure, in order to make assembling easier, not only electronic parts but also a modular jack are mounted on one board, and the board with the modular jack is covered with upper and lower covers (see Japanese Patent Publication No. Hei-5-3415/(1993)).

Please replace the Abstract at page 21, lines 1-16, with the following rewritten Abstract: